

CDx4HCT30 单路 8 输入与非门

1 特性

- 兼容 LSTTL 输入逻辑
 - $V_{IL(max)} = 0.8V$, $V_{IH(min)} = 2V$
- 兼容 CMOS 输入逻辑
 - 在电压为 V_{OL} 、 V_{OH} 时, $I_I \leq 1\mu A$
- 缓冲输入
- 工作电压为 4.5 V 至 5.5 V
- 宽工作温度范围: $-55^{\circ}C$ 至 $+125^{\circ}C$
- 支持多达 10 个 LSTTL 负载的扇出
- 与 LSTTL 逻辑 IC 相比, 可显著降低功耗

2 应用

- 警报/篡改检测电路
- S-R 锁存器

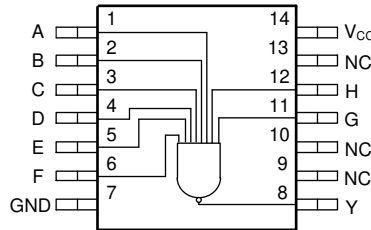
3 说明

该器件包含一个独立 8 输入与非门。每个逻辑门以正逻辑执行布尔函数 $Y = A \bullet B \bullet C \bullet D \bullet E \bullet F \bullet G \bullet H$ 。

器件信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
CD74HCT30M	SOIC (14)	8.70mm × 3.90mm
CD74HCT30E	PDIP (14)	19.30mm × 6.40mm
CD54HCT30F	CDIP (14)	21.30mm × 7.60mm

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。



功能引脚分配

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4 Revision History

DATE	REVISION	NOTES
June 2020	*	Initial release. Moved the HCT devices from the SCHS121 to a standalone data sheet.

5 Pin Configuration and Functions

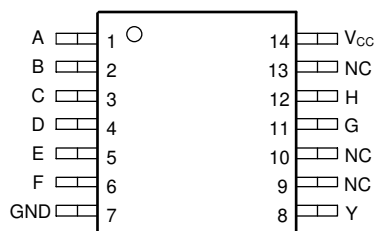


图 5-1. D, N, or J Package 14-Pin SOIC, PDIP, or CDIP Top View

Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
A	1	Input	Input A
B	2	Input	Input B
C	3	Input	Input C
D	4	Input	Input D
E	5	Input	Input E
F	6	Input	Input F
GND	7	—	Ground
Y	8	Output	Output Y
NC	9, 10, 13	—	Not internally connected
G	11	Input	Input G
H	12	Input	Input H
V _{CC}	14	—	Positive Supply

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage		- 0.5	7	V
I _{IK}	Input clamp current ⁽²⁾	V _I < - 0.5 V or V _I > V _{CC} + 0.5 V		±20	mA
I _{OK}	Output clamp current ⁽²⁾	V _O < - 0.5 V or V _O > V _{CC} + 0.5 V		±20	mA
I _O	Continuous output current	V _O > - 0.5 V or V _O < V _{CC} + 0.5 V		±25	mA
	Continuous current through V _{CC} or GND			±50	mA
T _J	Junction temperature ⁽³⁾	Plastic package		150	°C
		Hermetic package or die		175	
	Lead temperature (soldering 10s)	SOIC - Lead tips only		300	°C
T _{stg}	Storage temperature		- 65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) Guaranteed by design.

6.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5		5.5	V
V _{IH}	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2			V
V _{IL}	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V			0.8	V
V _I	Input voltage		0		V _{CC}	V
V _O	Output voltage		0		V _{CC}	V
t _i	Input transition time	V _{CC} = 4.5 V			500	ns
		V _{CC} = 5.5 V			400	
T _A	Operating free-air temperature		- 55		125	°C

6.3 Thermal Information

THERMAL METRIC ⁽¹⁾		CD74HCT30		UNIT
		N (PDIP)	D (SOIC)	
		14 PINS	14 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	64.7	101.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	52.4	58.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	44.4	57.7	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	32.0	19.6	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	44.2	57.3	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.4 Electrical Characteristics

over operating free-air temperature range; typical values measured at $T_A = 25^\circ\text{C}$ (unless otherwise noted).

PARAMETER		TEST CONDITIONS		V _{CC}	Operating free-air temperature (T _A)									UNIT
					25°C			– 40°C to 85°C			– 55°C to 125°C			
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V _{OH}	High-level output voltage	V _I = V _{IH} or V _{IL}	I _{OH} = – 20 μA	4.5 V	4.4			4.4			4.4			V
			I _{OH} = – 4 mA	4.5 V	3.98			3.84			3.7			
V _{OL}	Low-level output voltage	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	4.5 V				0.1					0.1	V
			I _{OL} = 4 mA	4.5 V				0.26			0.33			
I _I	Input leakage current	V _I = V _{CC} and GND	I _O = 0	5.5 V				±0.1			±1			μA
I _{CC}	Supply current	V _I = V _{CC} or GND	I _O = 0	5.5 V				2			20			μA
Δ I _{CC} (1)	Additional Quiescent Device Current Per Input Pin.	V _I = V _{CC} – 2.1		4.5 V to 5.5 V	100		360				450			μA
C _i	Input capacitance			5 V			10				10			pF

(1) For dual-supply systems theoretical worst case ($V_I = 2.4\ \text{V}$, $V_{CC} = 5.5\ \text{V}$) specification is 1.8 mA.

6.5 Switching Characteristics

over operating free-air temperature range; typical values measured at $T_A = 25^\circ\text{C}$ (unless otherwise noted).

PARAMETER		FROM	TO	TEST CONDITIO NS	V _{CC}	Operating free-air temperature (T _A)									UNIT
						25°C			– 40°C to 85°C			– 55°C to 125°C			
						MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
t _{pd}	Propagation delay	A or B	Y	C _L = 50 pF	4.5 V	28			35			42			ns
		A or B	Y	C _L = 15 pF	5 V	11									
t _t	Transition-time		Y	C _L = 50 pF	4.5 V	15			19			22			ns

6.6 Operating Characteristics

over operating free-air temperature range; typical values measured at $T_A = 25^\circ\text{C}$ (unless otherwise noted).

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
C_{pd}	Power dissipation capacitance per gate	No load	5 V		26		pF

6.7 Typical Characteristics

$T_A = 25^\circ\text{C}$

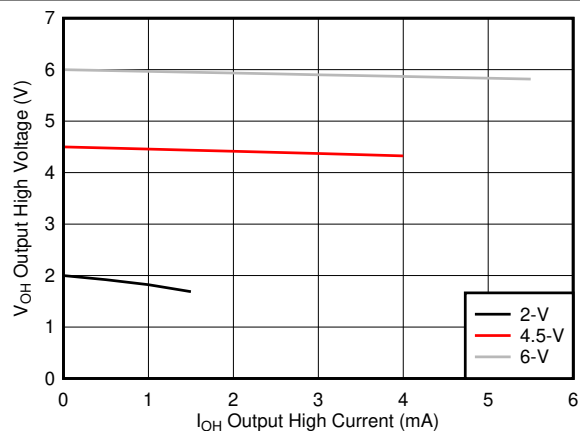


图 6-1. Typical output voltage in the high state (V_{OH})

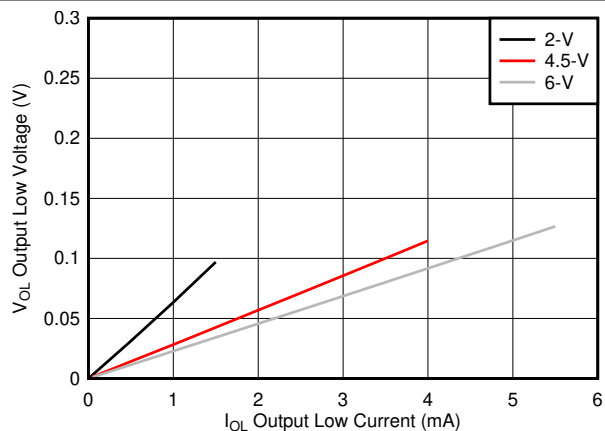
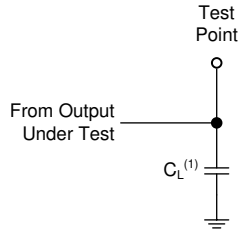


图 6-2. Typical output voltage in the low state (V_{OL})

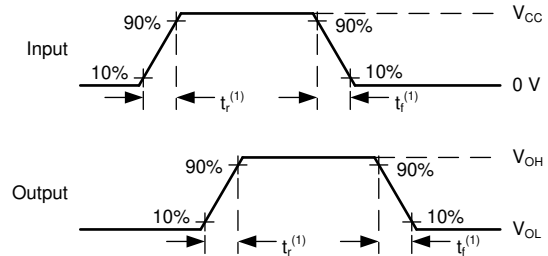
7 Parameter Measurement Information

- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_t < 6 \text{ ns}$.
- The outputs are measured one at a time, with one input transition per measurement.



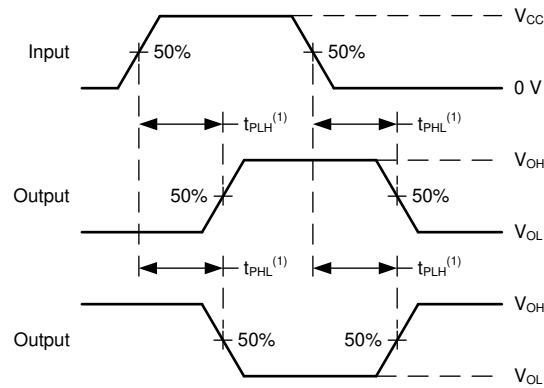
A. $C_L = 50 \text{ pF}$ and includes probe and jig capacitance.

图 7-1. Load Circuit



A. t_t is the greater of t_r and t_f .

图 7-2. Voltage Waveforms Transition Times



A. The maximum between t_{PLH} and t_{PHL} is used for t_{pd} .

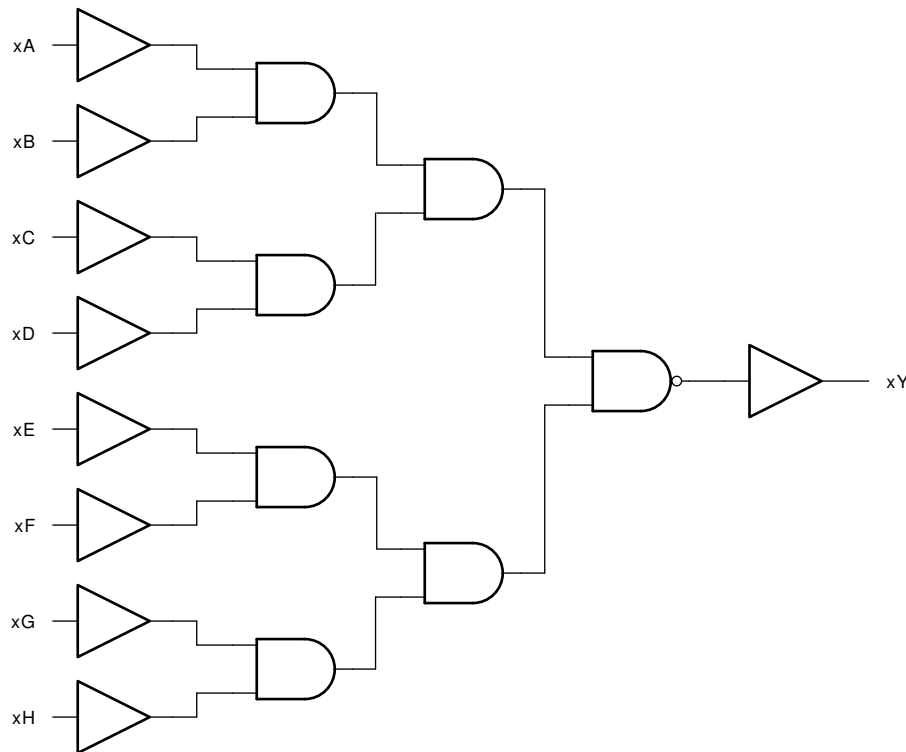
图 7-3. Voltage Waveforms Propagation Delays

8 Detailed Description

8.1 Overview

This device contains one independent 8-input NAND gate. Each gate performs the Boolean function $Y = A \cdot B \cdot C \cdot D \cdot E \cdot F \cdot G \cdot H$ in positive logic.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Balanced CMOS Push-Pull Outputs

A balanced output allows the device to sink and source similar currents. The drive capability of this device may create fast edges into light loads so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the output power of the device to be limited to avoid damage due to over-current. The electrical and thermal limits defined in the [§ 6.1](#) must be followed at all times.

The CD74HCT30 can drive a load with a total capacitance less than or equal to the maximum load listed in the [§ 6.5](#) connected to a high-impedance CMOS input while still meeting all of the datasheet specifications. Larger capacitive loads can be applied, however it is not recommended to exceed the provided load value. If larger capacitive loads are required, it is recommended to add a series resistor between the output and the capacitor to limit output current to the values given in the [§ 6.1](#).

8.3.2 TTL-Compatible CMOS Inputs

TTL-Compatible CMOS inputs are high impedance and are typically modeled as a resistor from the input to ground in parallel with the input capacitance given in the [§ 6.4](#). The worst case resistance is calculated with the maximum input voltage, given in the [§ 6.1](#), and the maximum input leakage current, given in the [§ 6.4](#), using ohm's law ($R = V \div I$).

Signals applied to the inputs need to have fast edge rates, as defined by $\Delta t / \Delta v$ in the [§ 6.2](#) to avoid excessive current consumption and oscillations. If a slow or noisy input signal is required, a device with a Schmitt-trigger input should be used to condition the input signal prior to the TTL-compatible CMOS input.

TTL-Compatible CMOS inputs have a lower threshold voltage than standard CMOS inputs to allow for compatibility with older bipolar logic devices. See the [节 6.2](#) for the valid input voltages for the CD74HCT30.

8.3.3 Clamp Diode Structure

The inputs and outputs to this device have both positive and negative clamping diodes as depicted in [图 8-1](#).

CAUTION

Voltages beyond the values specified in the [节 6.1](#) table can cause damage to the device. The recommended input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

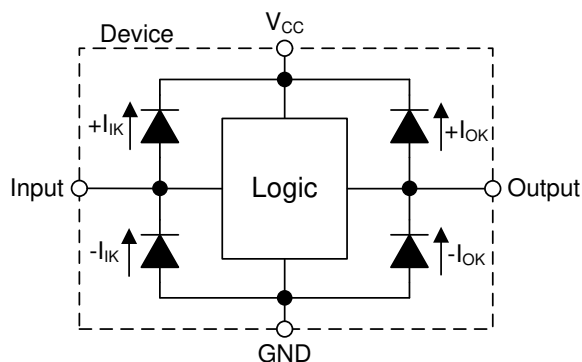


图 8-1. Electrical Placement of Clamping Diodes for Each Input and Output

8.4 Device Functional Modes

表 8-1. Function Table

INPUTS								OUTPUT
A	B	C	D	E	F	G	H	Y
H	H	H	H	H	H	H	H	L
L	X	X	X	X	X	X	X	H
X	L	X	X	X	X	X	X	H
X	X	L	X	X	X	X	X	H
X	X	X	L	X	X	X	X	H
X	X	X	X	L	X	X	X	H
X	X	X	X	X	L	X	X	H
X	X	X	X	X	X	L	X	H
X	X	X	X	X	X	X	L	H

9 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

9.1 Application Information

In this application, two 8-input NAND gates are used to create an active-low SR latch as shown in [图 9-1](#). Unused inputs can be tied together or to V_{CC} .

This device is used to drive the tamper indicator LED and provide one bit of data to the system controller. When the tamper switch outputs LOW, the output Q becomes HIGH. This output remains HIGH until the system controller addresses the event and sends a LOW signal to the R input which returns the Q output back to LOW.

9.2 Typical Application

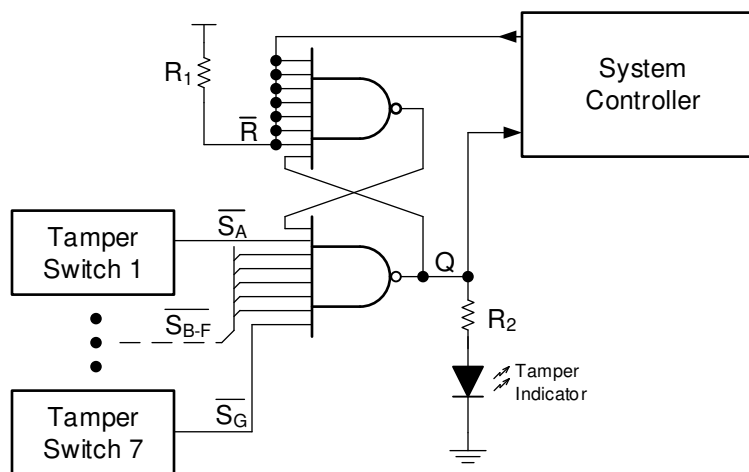


图 9-1. Typical application schematic

9.2.1 Design Requirements

9.2.1.1 Power Considerations

Ensure the desired supply voltage is within the range specified in the [节 6.2](#). The supply voltage sets the device's electrical characteristics as described in the [节 6.4](#).

The supply must be capable of sourcing current equal to the total current to be sourced by all outputs of the CD74HCT30 plus the maximum supply current, I_{CC} , listed in the [节 6.4](#). The logic device can only source or sink as much current as it is provided at the supply and ground pins, respectively. Be sure not to exceed the maximum total current through GND or V_{CC} listed in the [节 6.1](#).

Total power consumption can be calculated using the information provided in [CMOS Power Consumption and \$C_{pd}\$ Calculation](#).

Thermal increase can be calculated using the information provided in [Thermal Characteristics of Standard Linear and Logic \(SLL\) Packages and Devices](#).

CAUTION

The maximum junction temperature, $T_J(\text{max})$ listed in the [节 6.1](#), is an *additional limitation* to prevent damage to the device. Do not violate any values listed in the [节 6.1](#). These limits are provided to prevent damage to the device.

9.2.1.2 Input Considerations

Unused inputs must be terminated to either V_{CC} or ground. These can be directly terminated if the input is completely unused, or they can be connected with a pull-up or pull-down resistor if the input is to be used sometimes, but not always. A pull-up resistor is used for a default state of HIGH, and a pull-down resistor is used for a default state of LOW. The resistor size is limited by drive current of the controller, leakage current into the CD74HCT30, as specified in the [§ 6.4](#), and the desired input transition rate. A 10-k Ω resistor value is often used due to these factors.

Refer to the [§ 8.3](#) for additional information regarding the inputs for this device.

9.2.1.3 Output Considerations

The positive supply voltage is used to produce the output HIGH voltage. Drawing current from the output will decrease the output voltage as specified by the V_{OH} specification in the [§ 6.4](#). Similarly, the ground voltage is used to produce the output LOW voltage. Sinking current into the output will increase the output voltage as specified by the V_{OL} specification in the [§ 6.4](#).

Unused outputs can be left floating. Do not connect outputs directly to V_{CC} or ground.

Refer to [§ 8.3](#) for additional information regarding the outputs for this device.

9.2.2 Detailed Design Procedure

1. Add a decoupling capacitor from V_{CC} to GND. The capacitor needs to be placed physically close to the device and electrically close to both the V_{CC} and GND pins. An example layout is shown in the [§ 11](#).
2. Ensure the capacitive load at the output is ≤ 70 pF. This is not a hard limit, however it will ensure optimal performance. This can be accomplished by providing short, appropriately sized traces from the CD74HCT30 to the receiving device.
3. Ensure the resistive load at the output is larger than $(V_{CC} / I_O(\max)) \Omega$. This will ensure that the maximum output current from the [§ 6.1](#) is not violated. Most CMOS inputs have a resistive load measured in megaohms; much larger than the minimum calculated above.
4. Thermal issues are rarely a concern for logic gates, however the power consumption and thermal increase can be calculated using the steps provided in the application report, [CMOS Power Consumption and Cpd Calculation](#)

9.2.3 Application Curves

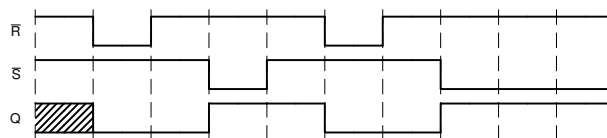


图 9-2. Typical application timing diagram

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [节 6.2](#). Each V_{CC} terminal should have a bypass capacitor to prevent power disturbance. A 0.1- μ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in [图 11-1](#).

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

- [HCMOS Design Considerations](#)
- [CMOS Power Consumption and CPD Calculation](#)
- [Designing with Logic](#)

12.2 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

12.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

12.5 术语表

TI 术语表 本术语表列出并解释了术语、首字母缩略词和定义。

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8974601CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8974601CA CD54HCT30F3A	Samples
CD54HCT30F3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8974601CA CD54HCT30F3A	Samples
CD74HCT30E	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT30E	Samples
CD74HCT30M	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT30M	Samples
CD74HCT30M96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT30M	Samples
CD74HCT30MT	ACTIVE	SOIC	D	14	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT30M	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD54HCT30, CD74HCT30 :

- Catalog : [CD74HCT30](#)
- Military : [CD54HCT30](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

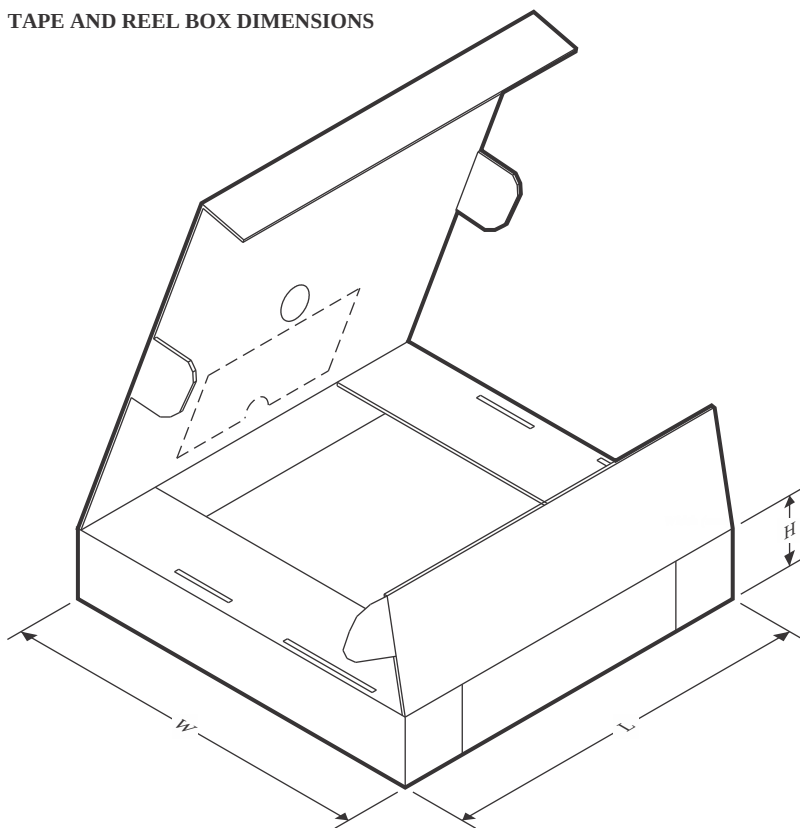
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HCT30M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD74HCT30MT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HCT30M96	SOIC	D	14	2500	356.0	356.0	35.0
CD74HCT30MT	SOIC	D	14	250	210.0	185.0	35.0

TUBE



*All dimensions are nominal

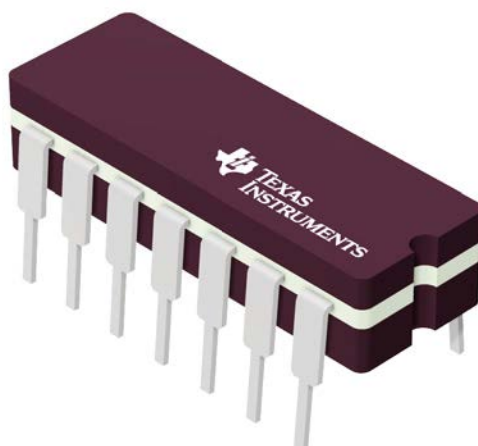
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
CD74HCT30E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HCT30E	N	PDIP	14	25	506	13.97	11230	4.32
CD74HCT30M	D	SOIC	14	50	506.6	8	3940	4.32

J 14

GENERIC PACKAGE VIEW

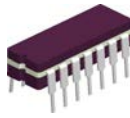
CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE

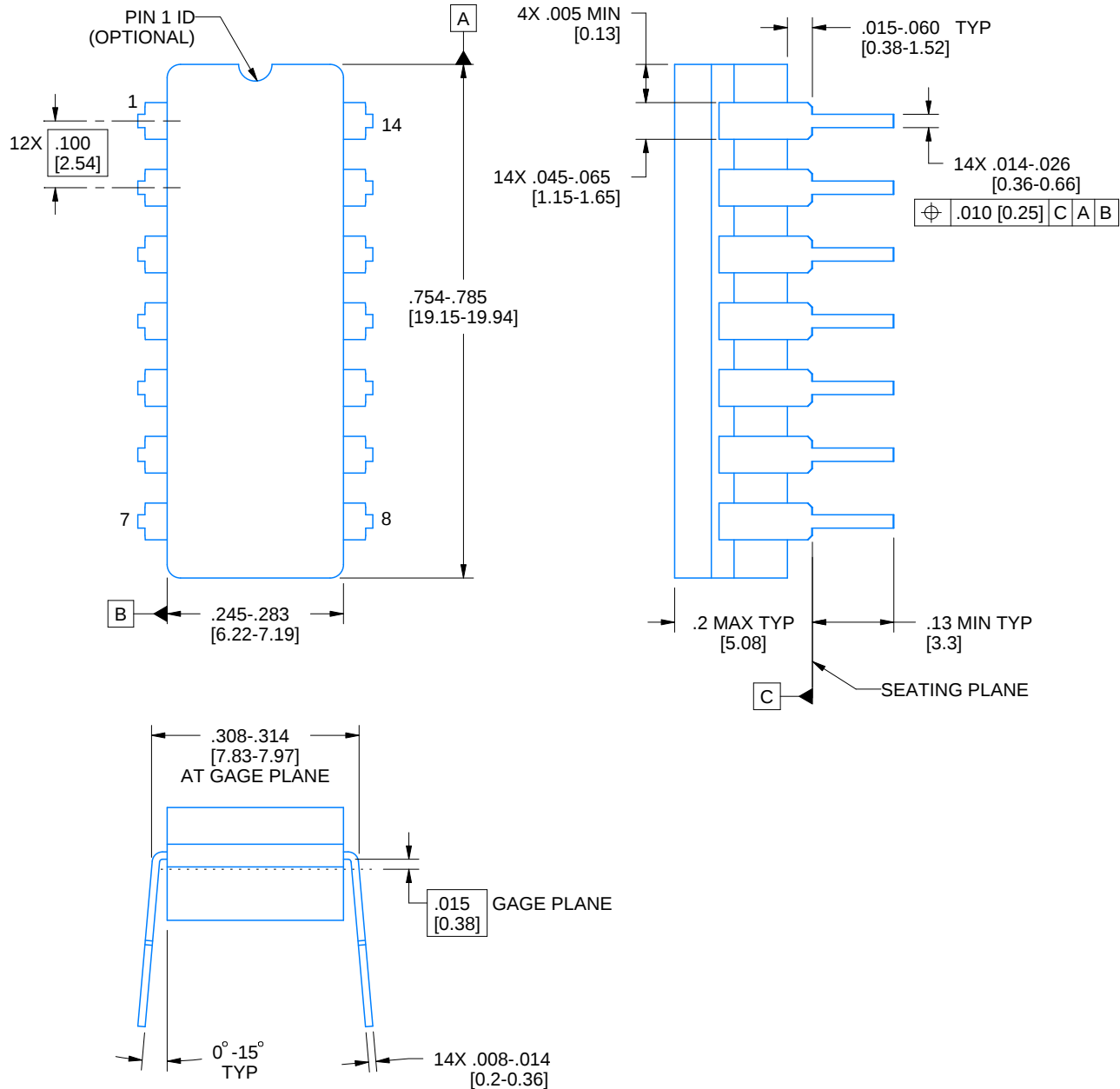


Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A**PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

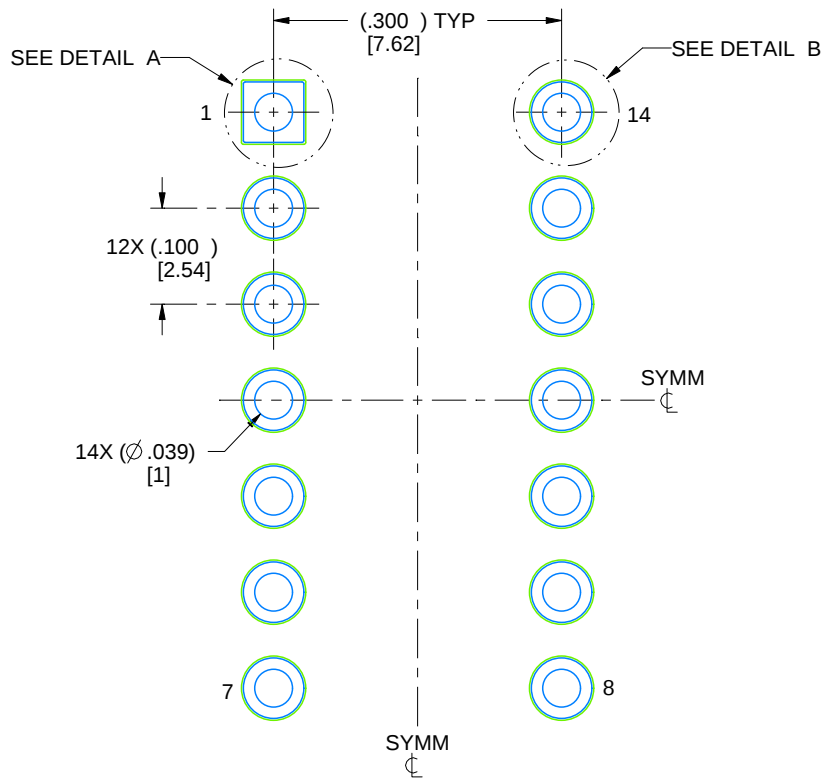
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

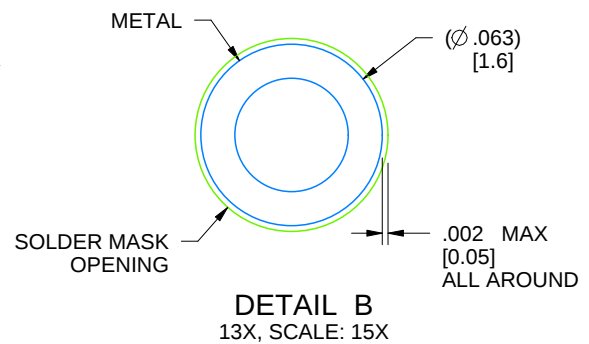
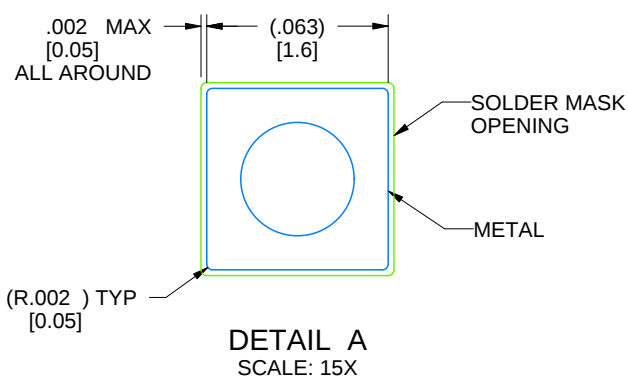
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



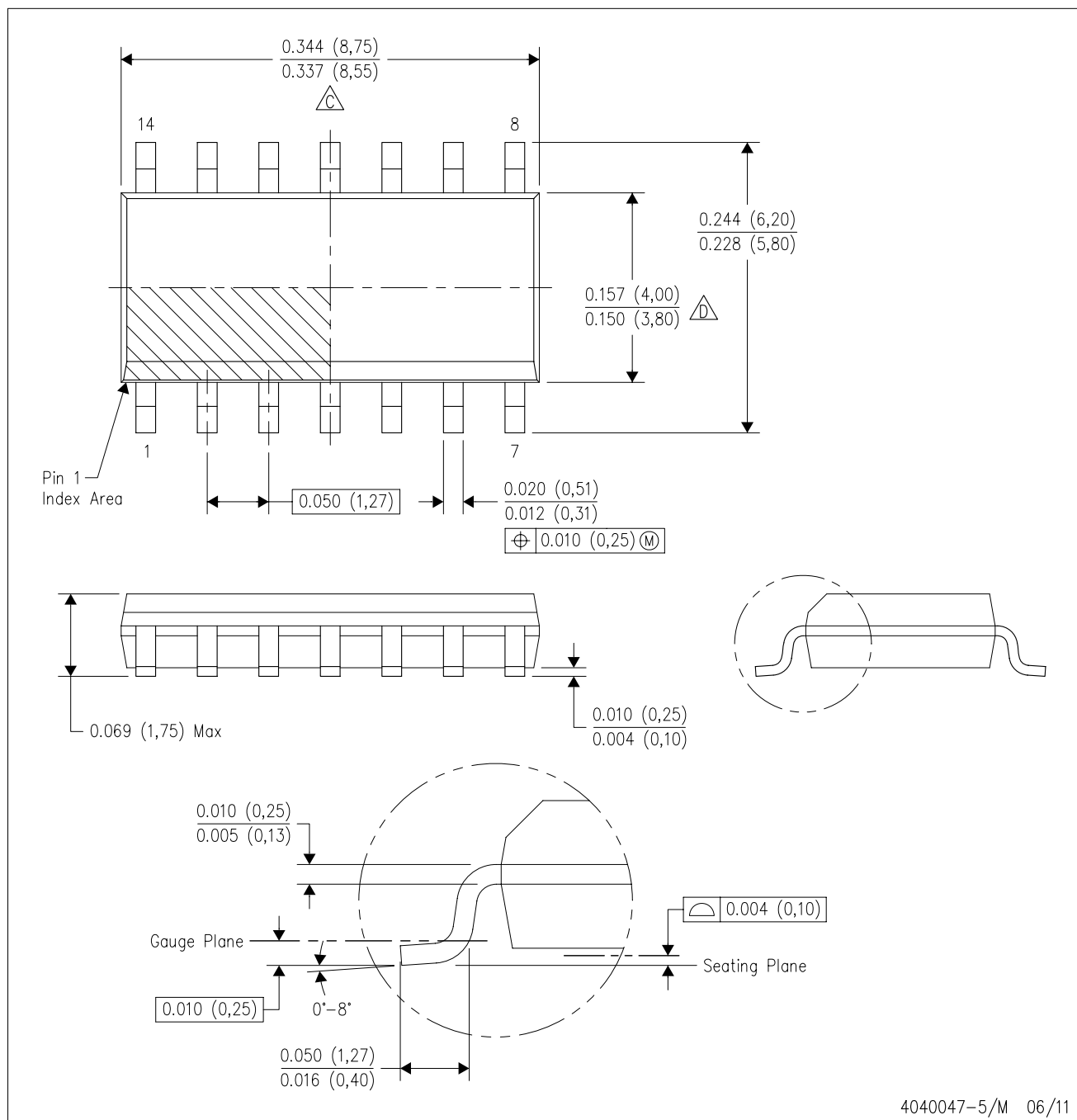
LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



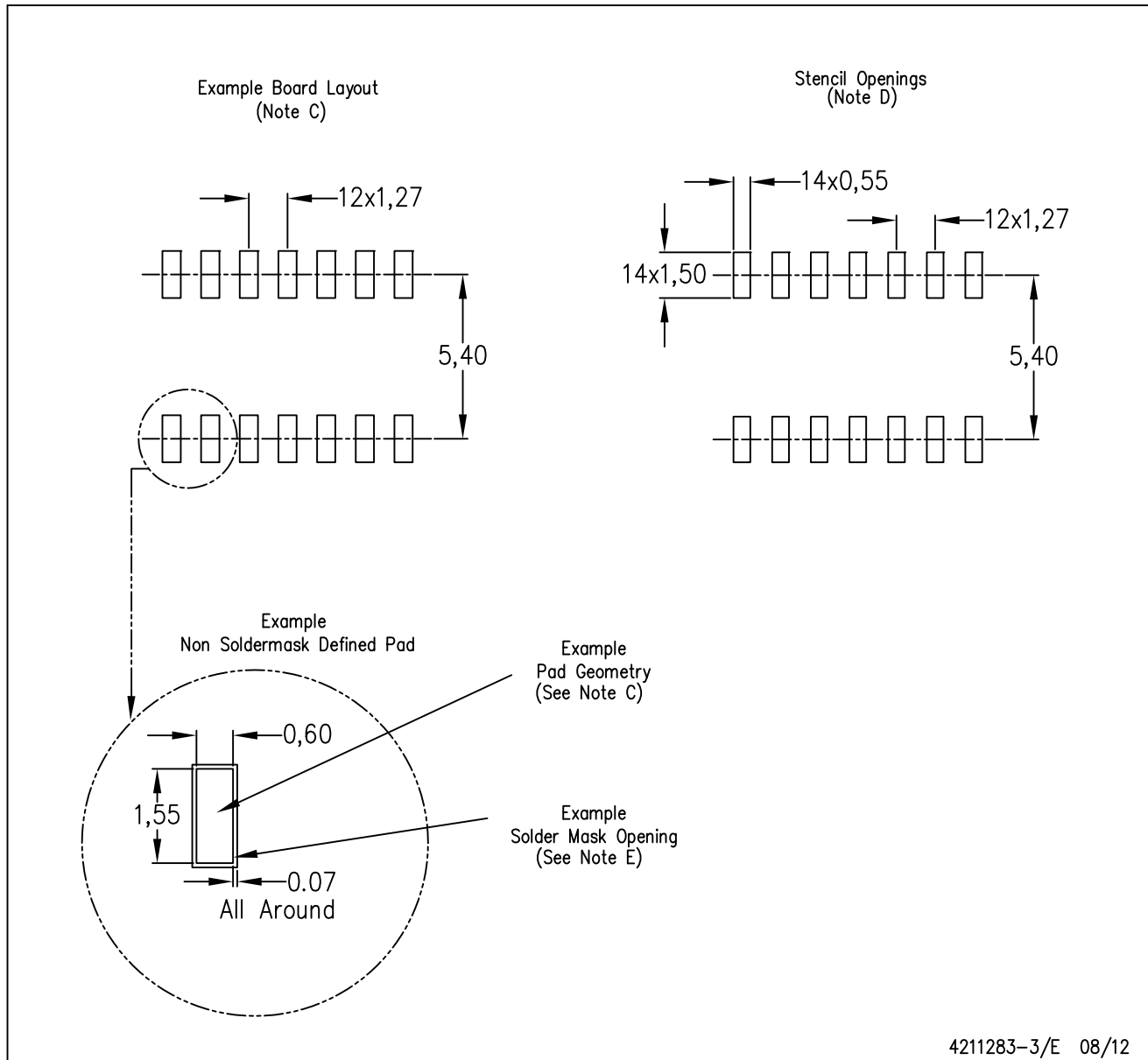
4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

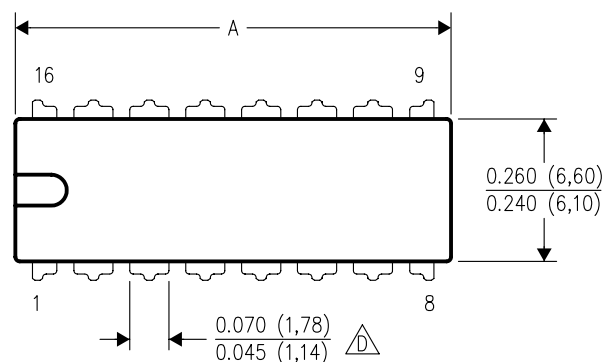


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

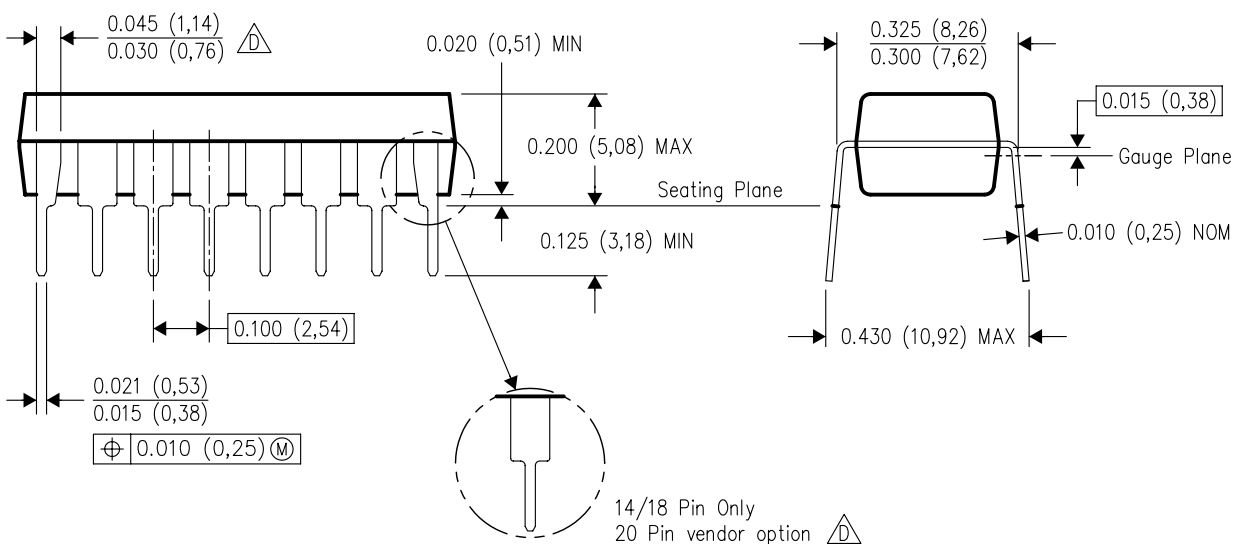
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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